

AMENDMENTS TO CLAIMS

Claim 1 (Currently Amended) A method for manufacturing a printed wiring board, ~~including the steps of:~~ board which includes forming a thermosetting resin layer so as to fill spaces between circuit patterns formed on a surface of the printed wiring board, ~~board~~, heating and curing the resin layer, layer, and then polishing said the cured resin layer covering said the circuit patterns, thereby exposing said the circuit patterns, wherein said the step of heating and curing said the resin layer comprises the following steps:

maintaining said the resin layer at a non-curable temperature where said the resin layer is pressed via a smoothing plate in a reduced pressure environment (step 1);

heating said the resin layer in said the pressed state to a curing temperature at which said the resin layer is cured (step 2);

introducing outside air ~~to eliminate~~ into the reduced pressure environment while maintaining said the pressed state and said the curing temperature (step 3);

reducing the pressure applied to said the smoothing plate while maintaining said the curing temperature (step 4); and

cooling said the resin layer (step 5).

Claim 2 (Currently Amended) The method for manufacturing a printed wiring board according to claim 1, wherein ~~in said step 1 the an~~ applied pressure ~~of to~~ the smoothing plate is increased in predetermined steps.

Claim 3 (Currently Amended) The method for manufacturing a printed wiring board according to claim 2, wherein said the resin layer is formed by adhering a liquid resin to said the printed wiring board so as to fill spaces between said the circuit patterns, and wherein a metallic foil with a roughened surface facing said the resin layer is superposed on the resin layer.

Claim 4 (Currently Amended) The method for manufacturing a printed wiring board

according to claim 1, wherein saidthe resin layer is formed by superposing a semi-cured resin sheet on the printed wiring board, and wherein a metallic foil with a roughened surface facing saidthe resin layer is superposed on the resin layer.

Claim 5 (Currently Amended) The method for manufacturing a printed wiring board according to claim 3, wherein saidthe metallic foil is formed with a different type of metal than saidthe circuit patterns.

Claim 6 (Currently Amended) The method for manufacturing a printed wiring board according to claim 4, wherein saidthe metallic foil is formed with a different type of metal than saidthe circuit patterns.

Claim 7 (Currently Amended) The method for manufacturing a printed wiring board according to claim 1 wherein saidthe reduced pressure environment is provided by a reduced pressure chamber.

Claim 8 (Currently Amended) The method for manufacturing a printed wiring board according to claim 1, wherein saidthe resin layer is formed by adhering a liquid resin to saidthe printed wiring board so as to fill spaces between saidthe circuit patterns, and wherein a metallic foil with a roughened surface facing saidthe resin layer is superposed on the resin layer.

Claim 9 (Currently Amended) The method for manufacturing a printed wiring board according to claim 8, wherein saidthe metallic foil is formed with a different type of metal than saidthe circuit patterns.

Claim 10 (Currently Amended) The method for manufacturing a printed wiring board according to claim 2, wherein saidthe resin layer is formed by superposing a semi-cured resin sheet on the printed wiring board, and wherein a metallic foil with a roughened surface facing

saidthe resin layer is superposed on the resin layer.

Claim 11 (Currently Amended) The method for manufacturing a printed wiring board according to claim 10, wherein saidthe metallic foil is formed with a different type of metal than saidthe circuit patterns.

Claims 12-19 (Canceled)